

Chip Scale Review

2015 Editorial Calendar

January • February

Semiconductor industry market update

Next generation device packaging

3D TSVs

Bonding challenges for 3D ICs

3D topography inspection for HVM

MEMS packaging technologies

Wafer probing

Advances in test and burn-in sockets

- **SEMI European 3D TSV Summit**
Grenoble, France (Jan 19-21)
- **APEX Expo**
San Diego, CA (February 24-26)
- **BiTS Workshop**
Mesa, AZ (March 15-18)
- **IMAPS Device Packaging (DPC)**
Fountain Hills, AZ (March 16-19)
- **SEMICON China**
Shanghai China (March 17-19)
- **Productronica China**
Shanghai China (March 17-19)

International Directory of Test and Burn-in Socket Suppliers

Ad Space Close Jan 6 - Ad Materials Deadline Jan 9

March • April

Future of mobile packaging & integration challenges

RF probe technologies

Electronic packaging materials

FOWLP technology

Flip-chip packaging

3D stacked ICs

Cu pillar technology

OSATS update

- **SEMICON South East Asia**
Penang, Malaysia (Apr 22-24)

International Directory of IC Packaging Foundries

Ad Space Close Feb 13 - Materials Close Feb 19

May • June

Interconnect technology

Thermal management of ICs

Interposer reliability

Wafer-level CSPs

Thin wafer-handling

MEMS Report Card

Dispensing technologies

Reducing the cost-of-test

Burn-in & test of packaged ICs*

Inline monitoring of advanced packaging processes

- **MEPTEC MEMS Technology**
San Jose, CA (May 20)
- **IoT Symposium**
San Jose, CA (May 21)
- **ECTC**
San Diego, CA (May 26-29)
- **IMAPS Advanced Technology Workshop**
Dearborn, MI (June 3-4)
- **IEEE/SW Test Workshop (SWTW)**
San Diego, CA (June 7-10)
- **SEMI – Packaging Technical Seminar**
Porto, Portugal (June 18)
- **SEMICON West**
San Francisco, CA (July 14-16)

*Awarded to best paper from BiTS Workshop 2015

Ad Space Close April 4 - Ad Materials Close April 10

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2015 Editorial Calendar

July • August

Plasma cleaning technologies	<ul style="list-style-type: none"> • SEMICON Taiwan Taipei, Taiwan (Sept 2-4) • MEPTEC Medical Microelectronics Conference Portland, OR (Sept 16-17) • SEMI European MEMS Summit Milan, Italy (Sept 17-18)
Failure analysis	
Collaboration in materials and processing technology	
Metrology & defect inspection	
Discrete power devices	
Cu pillar bumping	
MEMS IoT	
Solder reliability	

Ad Space Close Jun 6 - Ad Materials Close Jun 12

September • October

System scaling for smart mobile systems	<ul style="list-style-type: none"> • SEMICON Europa Dresden, Germany (Oct 6-8) • International Test Conference (ITC) Anaheim, CA (Oct 6 - 8) • IWLPC-International Wafer-Level Packaging Conference & Exhibition San Jose, CA (Oct 13 -15) • IMAPS 2015 Orlando, FL (Oct 26-29) • Productronica Munich, Germany (Nov 10-13) • MEMS Executive Congress Napa, CA (TBD)
Interposers	
Next generation SiP	
Wafer-level packaging processes and performance	
Test trends	
Fan out wafer level packaging	
Wirebonding	
Design-for-test for stacked ICs	
Packaging, assembly and test in Europe	

Ad Space Close Aug 15 - Ad Materials Close Aug 21

November • December

Recent advances in 3D package reliability	<ul style="list-style-type: none"> • RTI 3D ASIP Conference Burlingame, CA (Dec 9-11) • SEMICON Japan Tokyo, Japan (Dec 16-18) • SEMI European 3D TSV Summit 2016 Grenoble, France (TBD)
Die stacking	
Heterogeneous integration	
Future of packaging	
3D IC standards update	
Underfill, encapsulants, and adhesives	
PoP	
MEMS automotive applications	

Ad Space Close Oct 10 - Materials Close Oct 16

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